



511.41182X00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: H. YASUYUKI, et al

Serial No.: 10/073,309

Filed: February 13, 2002

For: RESIN COMPOSITION, AND USE AND METHOD FOR PREPARING
THE SAME

Group: Not assigned

Examiner: Not assigned

AB/CA
3/26/02
9c

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

March 18, 2002

Sir:

Prior to examination, please amend the above-identified application as follows.

IN THE CLAIMS

Please amend the claims as follows:

1. (Amended) A resin composition comprising:
an epoxy resin,
an amine-type curing agent,
an organophosphorous compound having a structure represented by formula 1:

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